

SLOVENSKI STANDARD
SIST EN IEC 62680-1-2:2021**01-december-2021****Nadomešča:****SIST EN IEC 62680-1-2:2020**

Vmesniki univerzalnega serijskega vodila za prenos podatkov in napajanje - 1-2. del: Skupne komponente - Specifikacija za zagotavljanje napajanja prek USB (IEC 62680-1-2:2021)

Universal serial bus interfaces for data and power - Part 1-2: Common components - USB Power Delivery specification (IEC 62680-1-2:2021)

Schnittstellen des Universellen Seriellen Busses für Daten und Energie - Teil 1-2: Gemeinsame Komponenten - Festlegung für die USB-Stromversorgung (IEC 62680-1-2:2021)

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Interfaces de bus universel en série pour les données et l'alimentation électrique - Partie 1-2: Composants communs - Spécification de l'alimentation électrique par port USB (IEC 62680-1-2:2021)**Ta slovenski standard je istoveten z: EN IEC 62680-1-2:2021****ICS:**

35.200 Vmesniška in povezovalna oprema Interface and interconnection equipment

SIST EN IEC 62680-1-2:2021**en,fr,de**

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EUROPEAN STANDARD

EN IEC 62680-1-2

NORME EUROPÉENNE

EUROPÄISCHE NORM

April 2021

ICS 29.220; 33.120; 35.200

Supersedes EN IEC 62680-1-2:2020 and all of its amendments and corrigenda (if any)

English Version

**Universal serial bus interfaces for data and power - Part 1-2:
Common components - USB Power Delivery specification
(IEC 62680-1-2:2021)**

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EN IEC 62680-1-2:2021 (E)**European foreword**

The text of document 100/3440/CDV, future edition 5 of IEC 62680-1-2, prepared by IEC/TC 100 "Audio, video and multimedia systems and equipment" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN IEC 62680-1-2:2021.

The following dates are fixed:

- latest date by which the document has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2022-01-20
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NORME INTERNATIONALE



Universal serial bus interfaces for data and power
Part 1-2: Common components – USB Power Delivery specification

Interfaces de bus universel en série pour les données et l'alimentation électrique
Partie 1-2: Composants communs – Spécification de l'alimentation électrique
par port USB

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UNIVERSAL SERIAL BUS INTERFACES FOR DATA AND POWER

Part 1-2: Common components – USB Power Delivery specification

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The text of this standard was prepared by the USB Implementers Forum (USB-IF). The structure and editorial rules used in this publication reflect the practice of the organization which submitted it.

The text of this International Standard is based on the following documents:

CDV	Report on voting
100/3440/CDV	100/3505/RVC

Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

This document has been drafted in accordance with the ISO/IEC Directives, Part 2.

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The IEC 62680 series is based on a series of specifications that were originally developed by the USB Implementers Forum (USB-IF). These specifications were submitted to the IEC under the auspices of a special agreement between the IEC and the USB-IF.

This standard is the USB-IF publication Universal Serial Bus Power Delivery Specification Revision 3.0, Version 2.0.

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